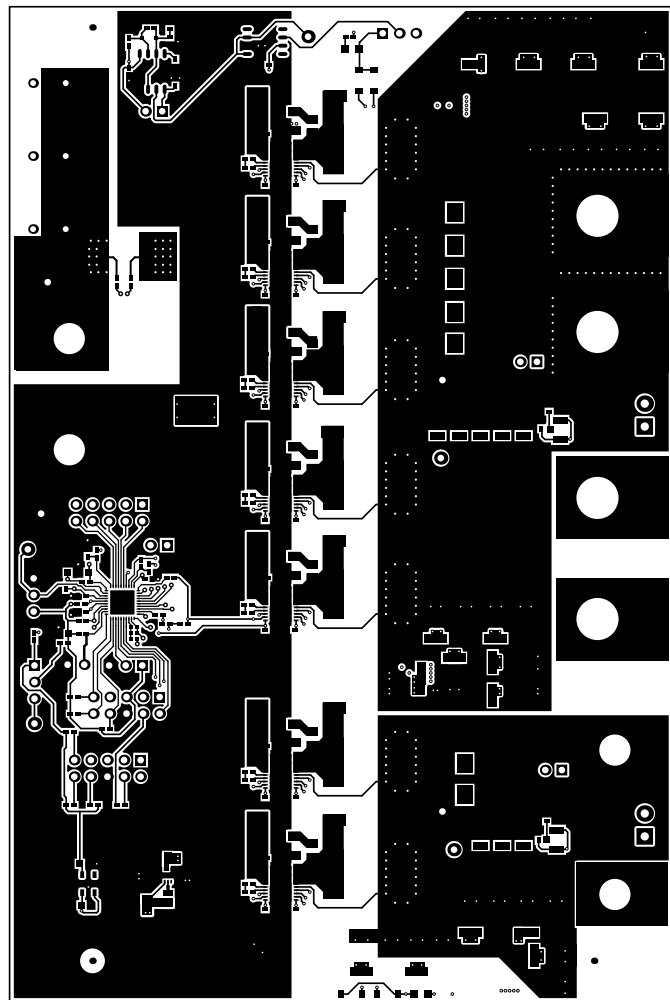
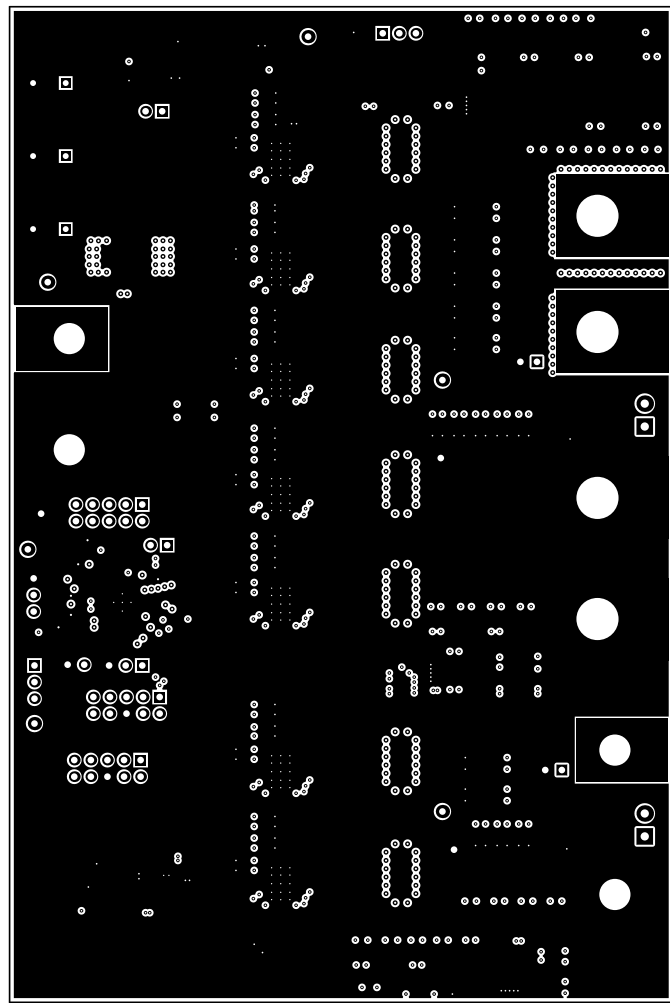


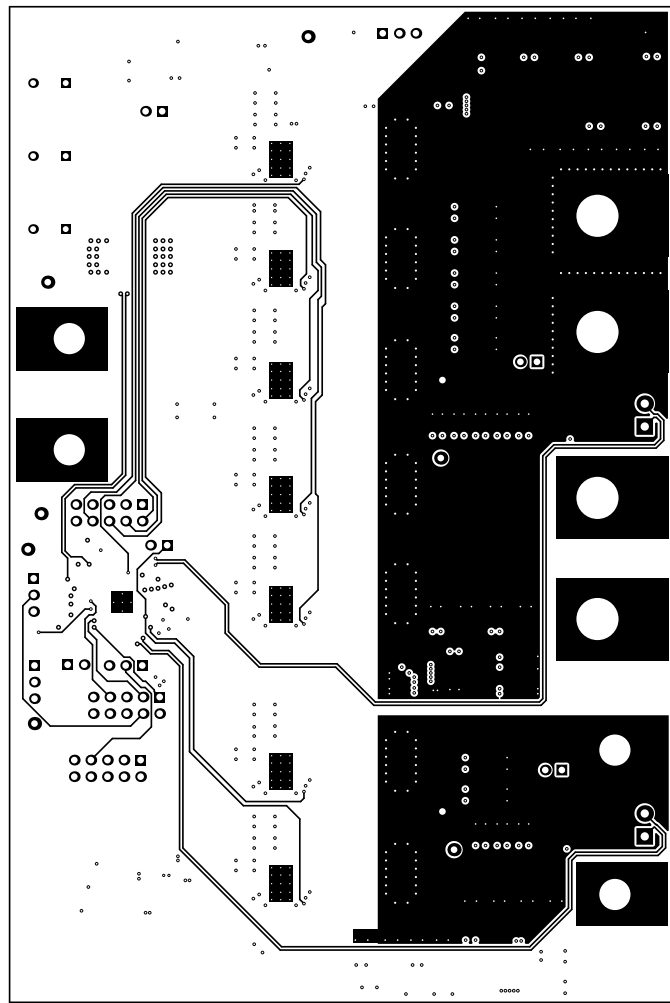
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20489	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: PMP20489		
PLOT NAME = Top Solder Mask	GENERATED : 9/29/2016 1:56:59 PM	TEXAS INSTRUMENTS	



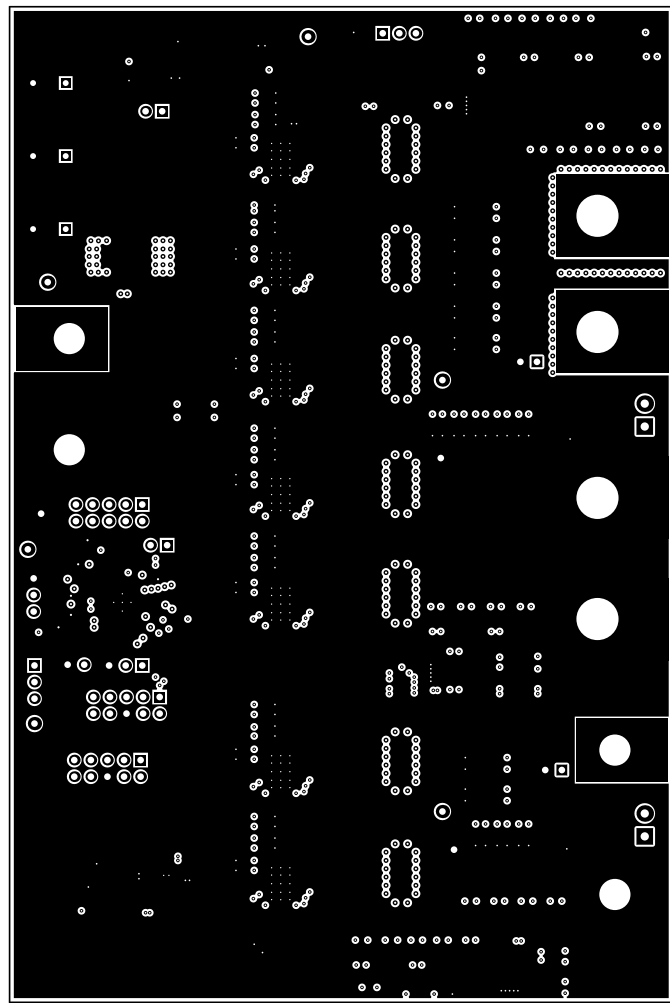
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20489	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: PMP20489		
PLOT NAME = Top Layer	GENERATED : 9/29/2016 1:57:07 PM	TEXAS INSTRUMENTS	



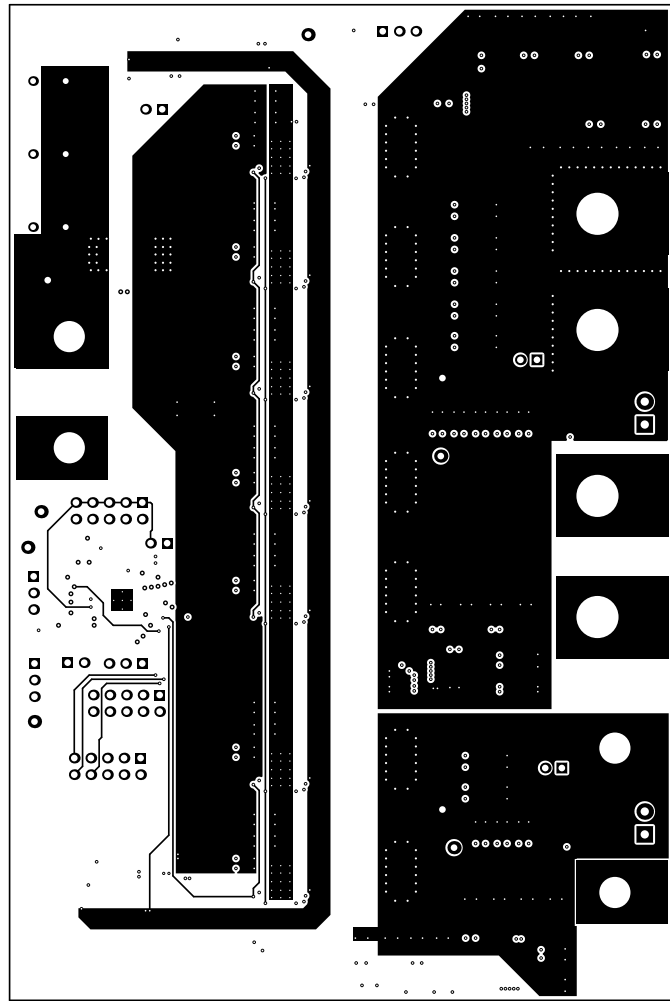
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20489	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Signal Layer 1	TID #: PMP20489		
PLOT NAME = Signal Layer 1	GENERATED : 9/29/2016 1:57:14 PM	TEXAS INSTRUMENTS	



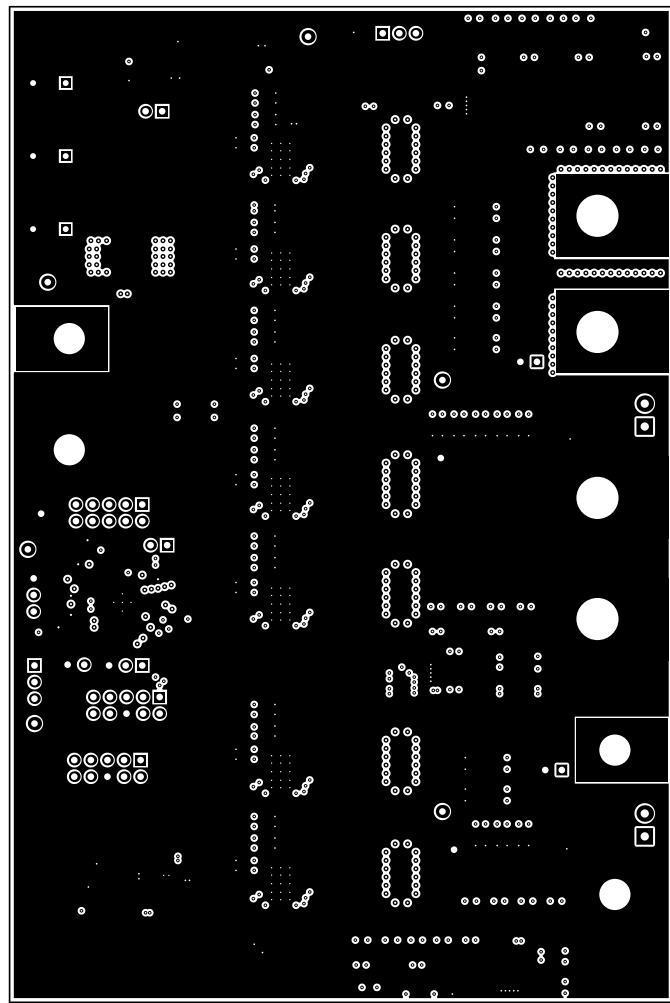
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20489	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Signal Layer 2	TID #: PMP20489		
PLOT NAME = Signal Layer 2	GENERATED : 9/29/2016 1:57:23 PM	TEXAS INSTRUMENTS	



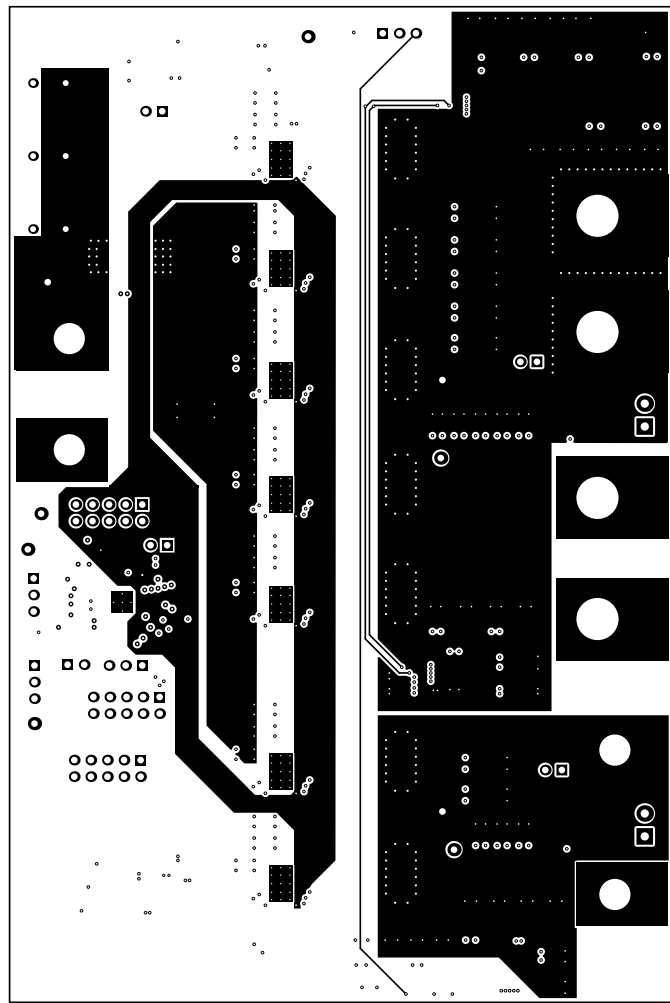
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20489	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Signal Layer 3	TID #: PMP20489		
PLOT NAME = Signal Layer 3	GENERATED : 9/29/2016	1:57:31 PM	TEXAS INSTRUMENTS



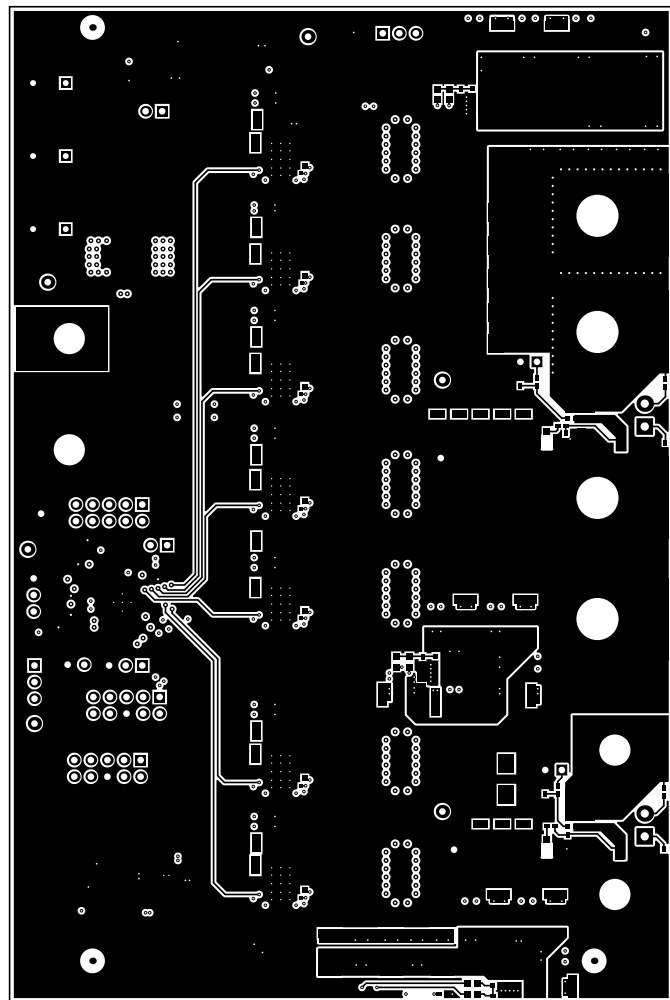
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20489	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Signal Layer 4	TID #: PMP20489		
PLOT NAME = Signal Layer 4	GENERATED : 9/29/2016 1:57:39 PM	TEXAS INSTRUMENTS	



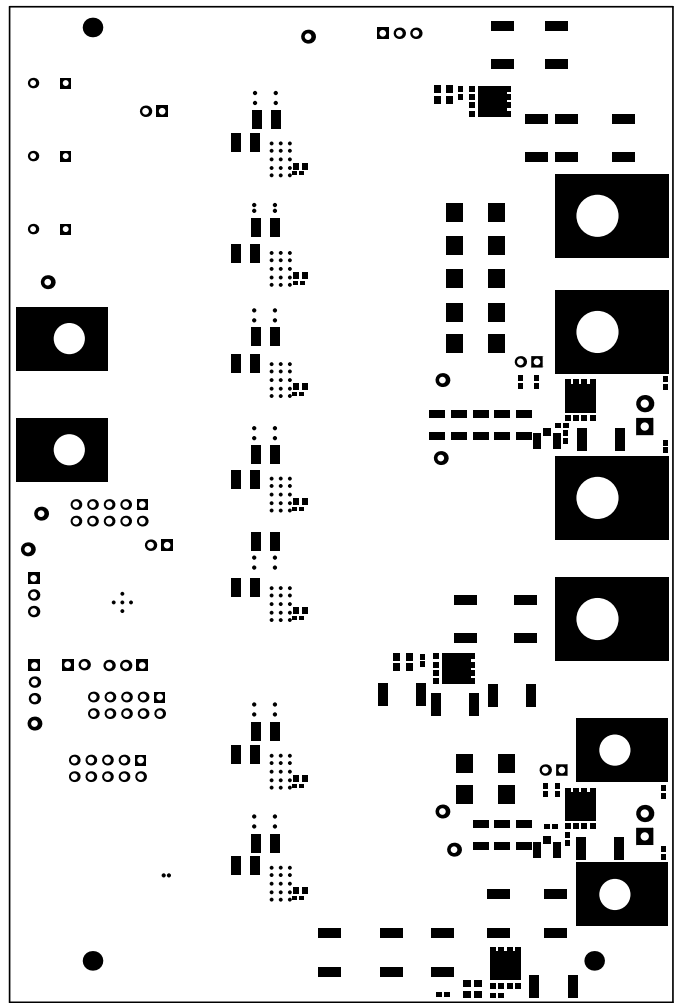
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20489	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Signal Layer 5	TID #: PMP20489		
PLOT NAME = Signal Layer 5	GENERATED : 9/29/2016 1:57:48 PM	TEXAS INSTRUMENTS	



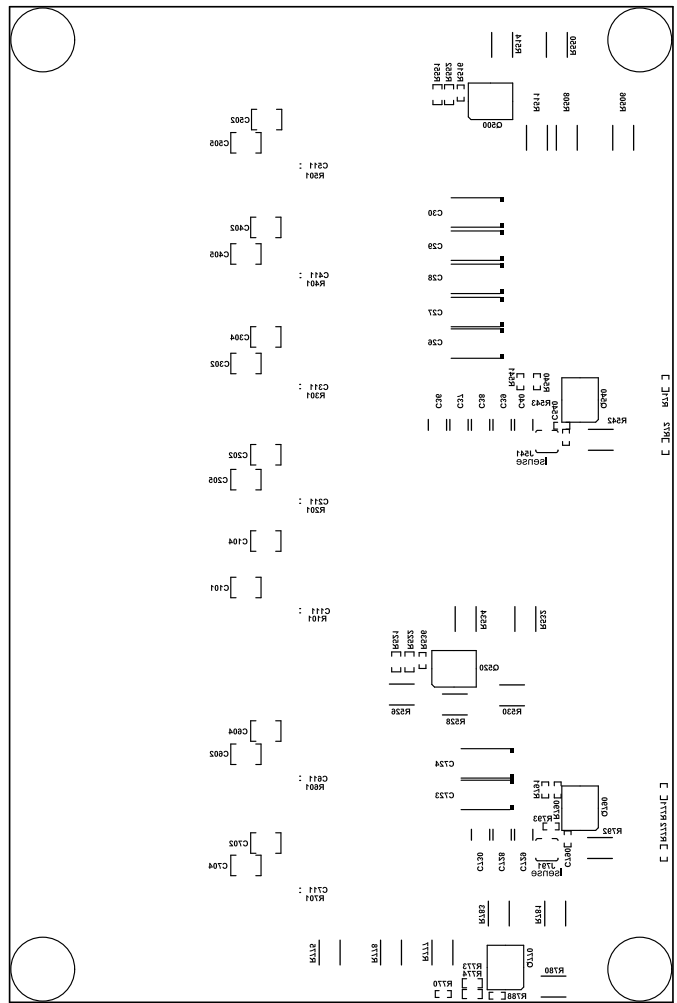
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20489	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Signal Layer 6	TID #: PMP20489		
PLOT NAME = Signal Layer 6	GENERATED : 9/29/2016 1:57:57 PM	TEXAS INSTRUMENTS	



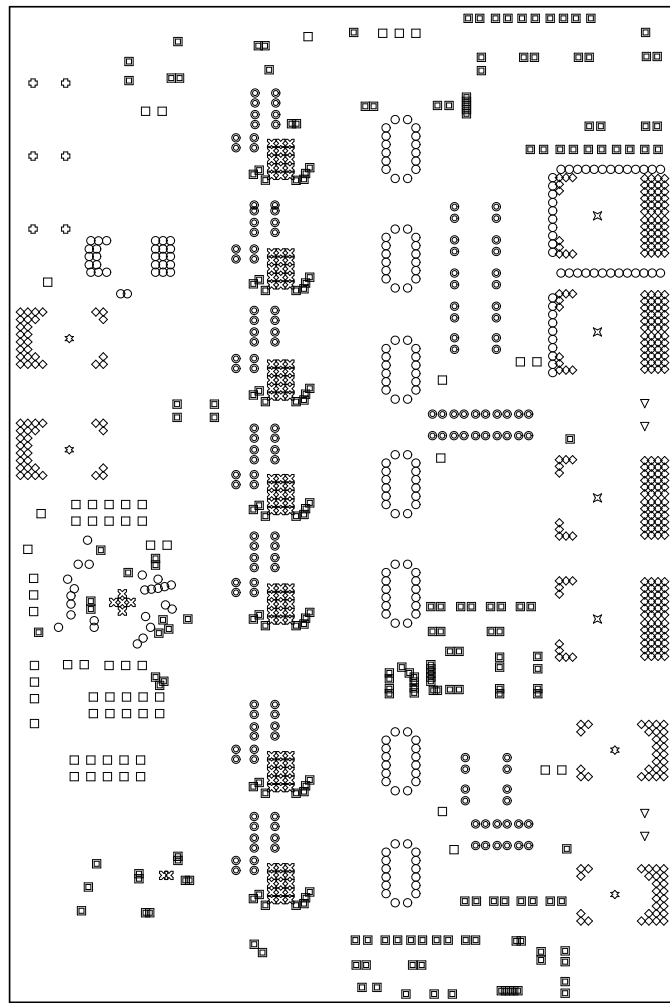
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20489	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: PMP20489		
PLOT NAME = Bottom Layer	GENERATED : 9/29/2016 1:58:06 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20489	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: PMP20489		
PLOT NAME = Bottom Solder Mask	GENERATED : 9/29/2016 1:58:15 PM	TEXAS INSTRUMENTS	



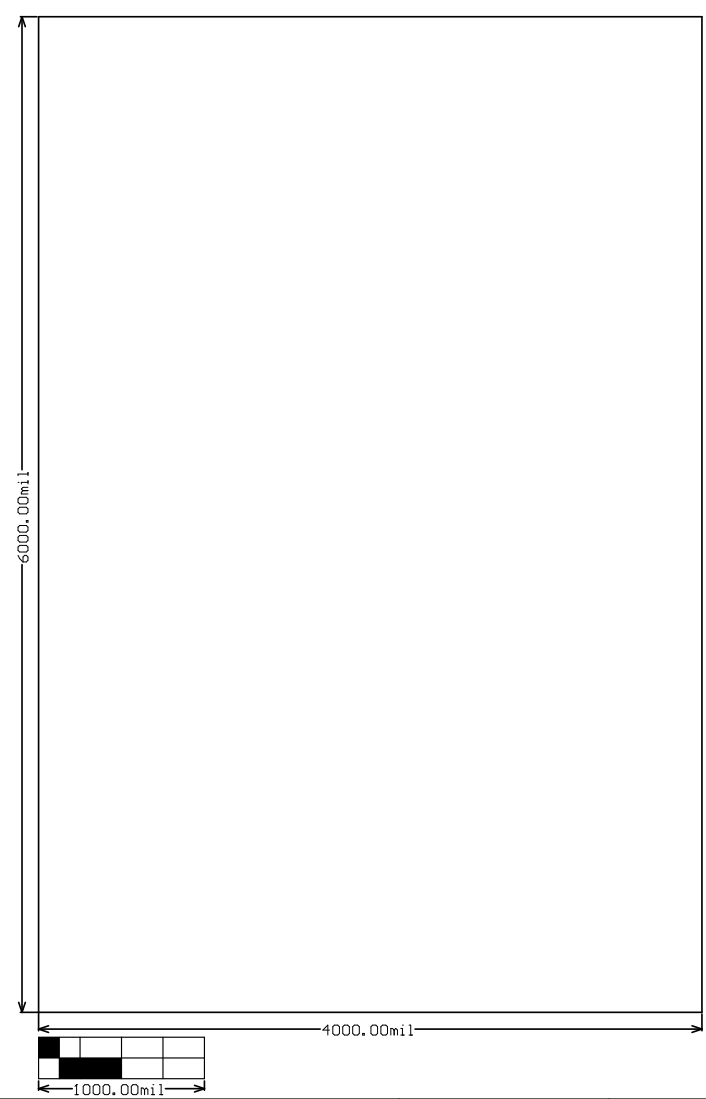
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20489	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: PMP20489		
PLOT NAME = Bottom Overlay	GENERATED : 9/29/2016	1:58:24 PM	TEXAS INSTRUMENTS



Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
⊗	112	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	
●	144	9.70mil (0.246mm)	PTH	Round	Top Layer - Bottom Layer	
■	216	10.00mil (0.254mm)	PTH	Round	Top Layer - Bottom Layer	
○	211	13.00mil (0.330mm)	PTH	Round	Top Layer - Bottom Layer	
◇	344	16.00mil (0.406mm)	PTH	Round	Top Layer - Bottom Layer	
⊕	6	35.43mil (0.900mm)	PTH	Round	Top Layer - Bottom Layer	
□	61	40.00mil (1.016mm)	PTH	Round	Top Layer - Bottom Layer	
▽	4	50.00mil (1.270mm)	PTH	Round	Top Layer - Bottom Layer	
☆	4	188.00mil (4.775mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	4	254.00mil (6.452mm)	PTH	Round	Top Layer - Bottom Layer	
	1106 Total					

ALL 9.7MIL-HOLED VIAS-IN-PADS MUST BE FILLED AND PLATED CLOSED

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20489	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: PMP20489		
PLOT NAME = Drill Drawing	GENERATED : 9/29/2016	1:58:34 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20489	REV: A	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: PMP20489		
PLOT NAME = Board Dimensions	GENERATED : 9/29/2016 1:58:44 PM	TEXAS INSTRUMENTS	

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